

FAX:13608178505 PAGE 1

<u>IN THE UNITED STATES PATENT AND TRADEMARK OFFICE</u>

In re Application of

TSI II. PATENT APPLICATION

Inventor:

Hirohiko Nishiki, James M.

Atkinson, and Yukihiko Nakata)

Serial No.: 10/040,646 ATTORNEY DOCKET No. SLA0452

August 5, 2003

Filed:

January 7, 2002

Group Art Unit: 1765

Title:

SYSTEM AND METHOD FOR)

ETCHING RESIN WITH AN

OZONE WET PROCESS

Examiner: Anita Karen

Alanko

CERTIFICATE OF TRANSMITTAL UNDER 37 C.F.R. § 1.8

is being facsimile transmitted to the I hereby certify that this correspondence United States Patent and Trademark Off ce at Fax. No. (703) 872-9310 on August/5, 2003.

> David C. Ripma, Reg. No. 27,672 Signature Date: August 5, 2003

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Non-Fee Amendment Hon. Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This communication responds to an Office Action dated July 30, 2003 in the above-identified patent application.

In the Office Action the Examiner requires restriction to one of the following inventions:

SIA0452 Restriction Resp

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Group I.

Claims 1-8 and 20, drawn to a method for cleaning

a resin residue; and

Group II.

Claims 9-19, drawn to a method for repairing a

resin interlayer surface.

OR MISO TIMES Applicants hereby elect to pursue the Group I claims, claims 1-8

and 20.

By:

Reg. No. 27,672

Respectfully submitte

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